ABSTRACT

UNDER BUMP METALLURGY IN INTEGRATED CIRCUITS

An integrated circuit package and method of manufacture is provided. A substrate having a number of contact pads exposed through a passivation layer thereon has a first under bump metallurgy layer over at least one of the contact pads. A top under bump metallurgy layer of copper having a thickness of less than about 800 angstroms is formed over the first under bump metallurgy layer. (Fig. 6)